



## Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ Idea for printed circuit board
- ◆ Glass passivated junction chip
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed  
260°C/10 seconds at terminals

## Mechanical Data

**Case :** Molded plastic body

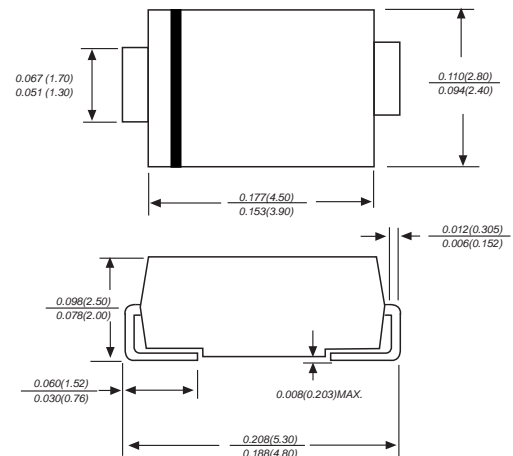
**Terminals :** Solder plated, solderable per MIL-STD-750, Method 2026

**Polarity :** Polarity symbol marking on body

**Mounting Position :** Any

**Weight :** 0.0023 ounce, 0.07 grams

## DO-214AC/SMA



Dimensions in inches and (millimeters)

## Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	GS2TA	GS2WA	GS2XA	GS2YA	UNITS
Maximum repetitive peak reverse voltage	$V_{RRM}$	1300	1600	1800	2000	V
Maximum RMS voltage	$V_{RMS}$	910	1120	1260	1400	V
Maximum DC blocking voltage	$V_{DC}$	1300	1600	1800	2000	V
Maximum average forward rectified current at $T_L=100^\circ\text{C}$	$I_{(AV)}$	2.0				A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	$I_{FSM}$	30.0				A
Maximum instantaneous forward voltage at 2.0A	$V_F$	1.1				V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$	$I_R$	2.0 200				$\mu\text{A}$
Typical junction capacitance (Note1)	$C_J$	48.0				pF
Typical thermal resistance	$R_{qJA}$	47.0				$^\circ\text{C/W}$
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +150				$^\circ\text{C}$

**Note:** 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

## Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

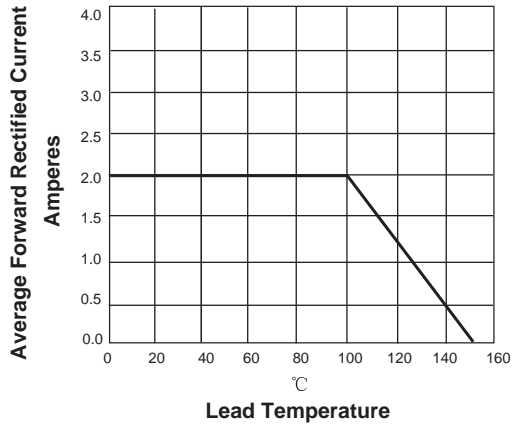


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

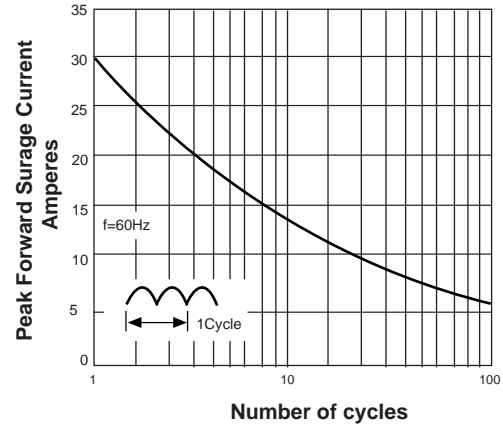


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

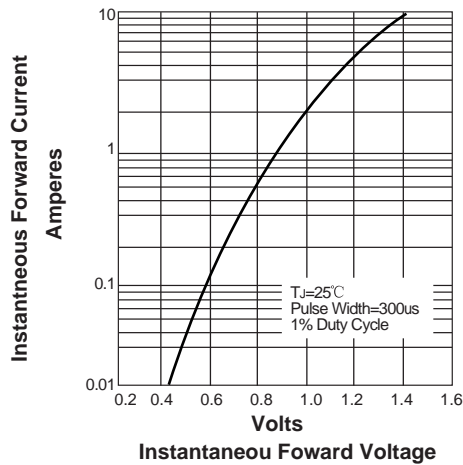
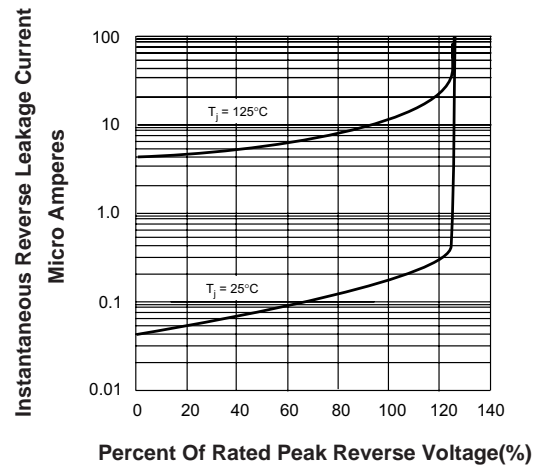
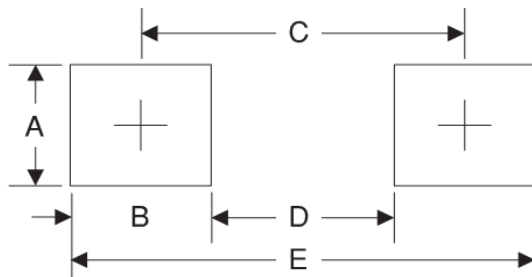


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS

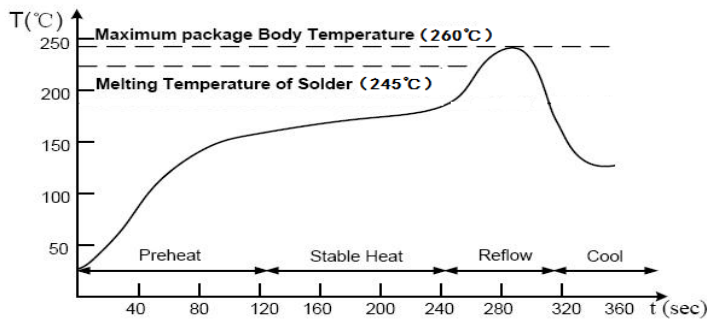


## Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.68	0.066
B	1.52	0.060
C	3.90	0.154
D	2.41	0.095
E	5.45	0.215

## Suggested Soldering Temperature Profile

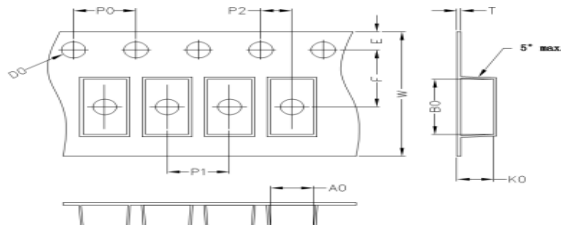


### Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 260°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

## Package Information

### Carrier Dimension(mm)



<b>A0</b>	<b>B0</b>	<b>K0</b>	<b>D0</b>	<b>E</b>	<b>F</b>
2.80	5.30	2.36	1.55	1.75	5.50
<b>P0</b>	<b>P1</b>	<b>P2</b>	<b>T</b>	<b>W</b>	<b>Tolerance</b>
4.0	4.0	2.0	0.25	12	0.1

### Package Specifications

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
SMA	11'	278	5	285	10	355*310*310	80
	13'	330	7.5	340	15	360*360*360	120

### NOTICE

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Shanghai Leiditech Electronic Co.,Ltd

Email: sale1@leiditech.com

Tel : +86- 021 50828806

Fax : +86- 021 50477059